TLVR Series

Molding Power Inductors

Size 100510

FEATURES

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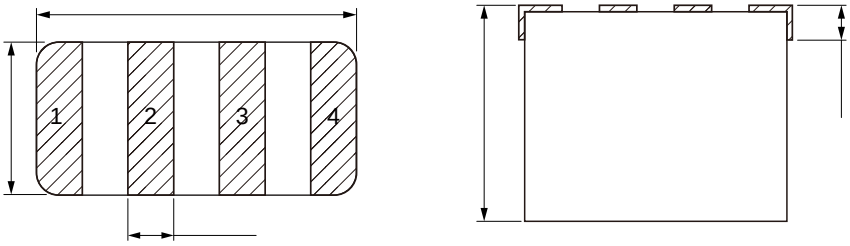
- Higher current carrying Capacity, lower DCR, and more e ciency.
- Opera ng temperature: -55 to +125 °C(Including self - temperature rise).
- Quan ty: 400PCS

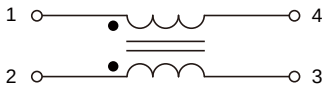
APPLICATION

- AI Servers, Data Centers, GPU/AI Accelerators.
- Desktop Motherboards, CPU/GPU Power Delivery.
- Mul -phase VRM, High-current DC-DC Converters.
- Networking Equipment, Communica on Infrastructure.

Dimensions: [mm]



Schematic:

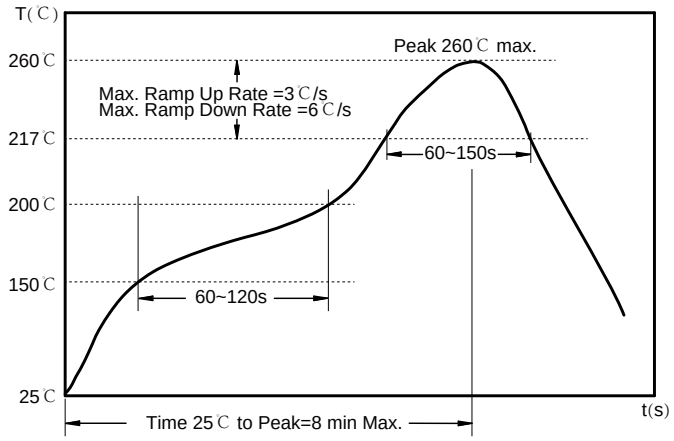


Electrical Properties:

Part No	Inductance (μH)	Min. (nH)	Resistance (mΩ)	Resistance (mΩ)	Rise Current	Satura on Current	Hi-Pot Min.	Min.

All test data is referenced to 25 °C ambient.
Saturation Current will cause L0 to drop approximately 30%.
Temperature Rise Current: The actual value of DC current when the temperature rise is △T=40 °C.
FLL: tested @100 kHz, 1.0 Vrms, Isat, applied for +25 °C.
Hi-Pot: as pass / fail judgement, tested @ 2s,2mA, between 2 windings.

Soldering Reflow:



Preheat condition: 150 ~200 ℃/ 60~120 sec.

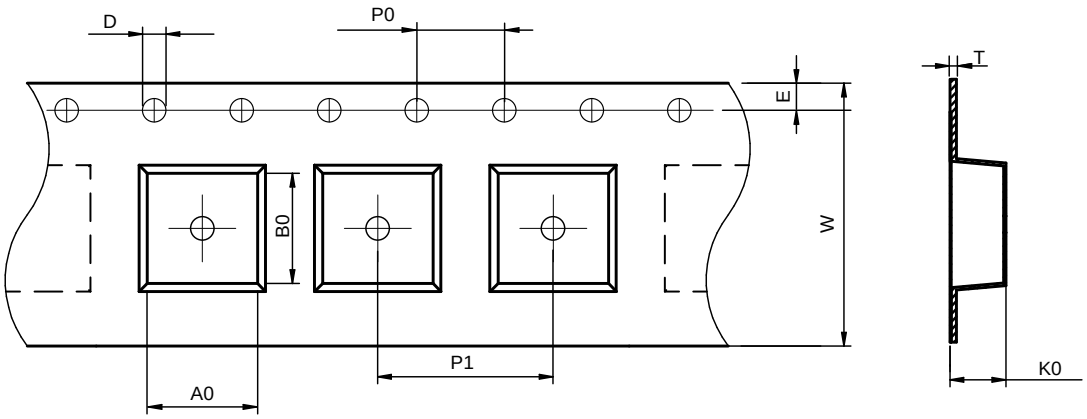
Allowed time above 217 ℃: 60~150 sec.

Max temperature: 260 ℃.

Time within 5 ℃ of actual Peak Temperature: 30 max. sec.

Packaging Information:

Tape Dimension:



A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)

Product Marking:

Marking	Printing Inductance)